Semiconductor Probes 0.50MM PITCH

101267 Ркове







PROBE SPECIFICATIONS

Minimum Device Pitch: 0.50mm (.020) Signal Path Length: 2.92mm (.115) Force per Contact: 24g (0.86 oz.), 27g (.94 oz.), 31.1g (1.10 oz.) or 37g (1.30 oz.) @ 0.38mm (.015) travel Device Compliance: 0.23mm (.009) DUT Board Compliance: 0.15mm (.006)

Operating Temperature:

-55°C to 150°C for stainless steel spring -55°C to 120°C for music wire spring Insertions: > 500,000

MATERIALS

Barrel: Full-hard beryllium copper, Endura plating Spring:

Stainless steel, gold plated – 24g & 27g spring Music wire, gold plated – 32g & 37g spring Device Side Contact: Full-hard beryllium copper, gold plated

Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

Typical Resistance: < 40 m Ω Current Carrying Capacity: 3.5 amps continuous (Current DC carry capability @ 80° C steady state) Pattern 2a: **Q O**.5mm pitch Characteristic Impedance: 61 Ω Time Delay: 18 pSec Loop Inductance: 1.12 nH Signal Pin to Return Capacitance: 0.30 pF

-1 dB Insertion Loss Bandwidth: > 20 GHz

How to Order				
Part No.	Device Side Tip	PCB Side Tip	Spring Force	
101267-200	Concave	Radius	24g	
101267-202	0.32 4-pt. Crown	Radius	24g	
101267-203	120° Spear	Radius	24g	
101267-206	0.32 4-pt. Crown	Radius	31.1g	
101267-208	0.20 4-pt. Crown	Radius	37g	
101267-209	0.20 4-pt. Crown	Radius	27g	

Specifications subject to change without notice. Dimensions in millimeters (inches)

PROBE SPECIFICATIONS

 $\begin{array}{l} \mbox{Minimum Device Pitch: } 0.50mm (.020) \\ \mbox{Signal Path Length: } 2.9mm (.114) \\ \mbox{Force per Contact: } 25.3g (0.89 oz.) or 30g (1.06 oz.) @ \\ 0.38mm (.015) travel \\ \mbox{Device Compliance: } 0.23mm (.009) \\ \mbox{DUT Board Compliance: } 0.15mm (.006) \\ \mbox{Operating Temperature: } \\ -55^{\circ}\mbox{C to } 150^{\circ}\mbox{C for stainless steel spring } \\ -55^{\circ}\mbox{C to } 120^{\circ}\mbox{C for music wire spring } \\ \mbox{Insertions: } > 500,000 \\ \end{array}$

MATERIALS

Barrel: Phosphorous bronze, gold plating Spring:

Stainless steel, gold plated – 25.3g spring Music wire, gold plated – 30g spring

Device Side Contact: Homogeneous alloy Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

How to Order				
Part No.	Device Side Tip	PCB Side Tip	Spring Force	
623-0326-H3	120° Spear	Radius	25.3g	
623-0326-H6	0.32 4-pt. Crown	Radius	25.3g	
623-0326-H9	0.20 4-pt. Crown	Radius	30g	

H3, H6 & H9 has the homogeneous alloy on the device side of the contact.

Prolonged exposure of greater than one hour reduces the maximum operating temperature of music wire springs to 85°C.

